Lattice Semiconductor Corporation - LCMXO2280E-3FTN256I Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Active
Number of LABs/CLBs	285
Number of Logic Elements/Cells	2280
Total RAM Bits	28262
Number of I/O	211
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-LBGA
Supplier Device Package	256-FTBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo2280e-3ftn256i

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The devices use look-up tables (LUTs) and embedded block memories traditionally associated with FPGAs for flexible and efficient logic implementation. Through non-volatile technology, the devices provide the single-chip, high-security, instant-on capabilities traditionally associated with CPLDs. Finally, advanced process technology and careful design will provide the high pin-to-pin performance also associated with CPLDs.

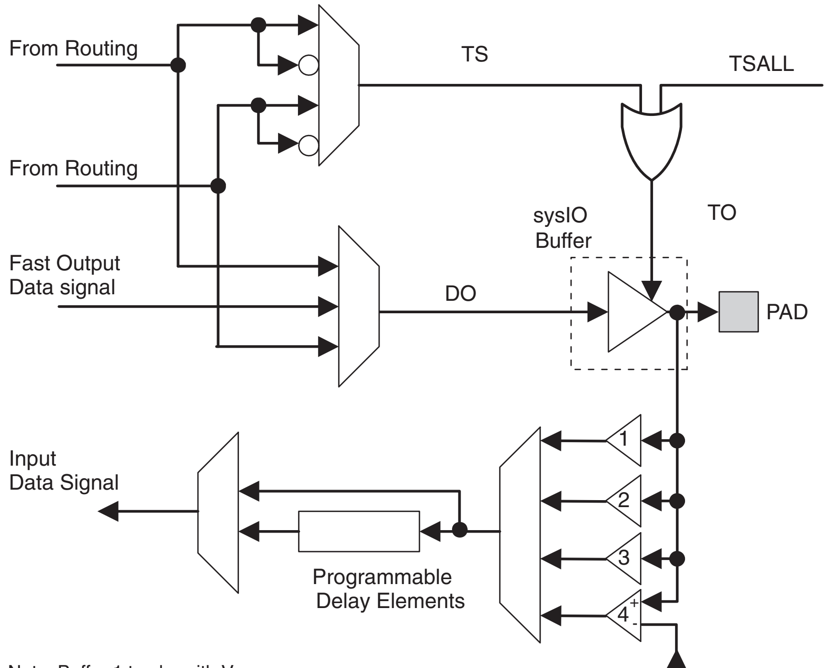
The ispLEVER® design tools from Lattice allow complex designs to be efficiently implemented using the MachXO family of devices. Popular logic synthesis tools provide synthesis library support for MachXO. The ispLEVER tools use the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the MachXO device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

output data signals are multiplexed and provide a single signal to the I/O pin via the sysIO buffer. Figure 2-17 shows the MachXO PIO logic.

The tristate control signal is multiplexed from the output data signals and their complements. In addition a global signal (TSALL) from a dedicated pad can be used to tristate the sysIO buffer.

The PIO receives an input signal from the pin via the sysIO buffer and provides this signal to the core of the device. In addition there are programmable elements that can be utilized by the design tools to avoid positive hold times.

Figure 2-17. MachXO PIO Block Diagram



Note: Buffer 1 tracks with V_{CCAUX}
Buffer 2 tracks with V_{CCIO}.
Buffer 3 tracks with internal 1.2V V_{REF}.
Buffer 4 is available in MachXO1200 and MachXO2280 devices only.

sysIO Buffer

Each I/O is associated with a flexible buffer referred to as a sysIO buffer. These buffers are arranged around the periphery of the device in groups referred to as Banks. The sysIO buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, TTL, BLVDS, LVDS and LVPECL.

In the MachXO devices, single-ended output buffers and ratioed input buffers (LVTTL, LVCMOS and PCI) are powered using V_{CCIO}. In addition to the Bank V_{CCIO} supplies, the MachXO devices have a V_{CC} core logic power supply, and a V_{CCAUX} supply that powers up a variety of internal circuits including all the differential and referenced input buffers.

MachXO256 and MachXO640 devices contain single-ended input buffers and single-ended output buffers with complementary outputs on all the I/O Banks.

MachXO1200 and MachXO2280 devices contain two types of sysIO buffer pairs.

1. **Top and Bottom sysIO Buffer Pairs**
   The sysIO buffer pairs in the top and bottom Banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (for ratioed or absolute input levels). The I/O pairs on the top and bottom

MachXO Family Data Sheet
DC and Switching Characteristics

June 2013 **Data Sheet DS1002**

Absolute Maximum Ratings[1, 2, 3]

	LCMXO E (1.2V)	LCMXO C (1.8V/2.5V/3.3V)
Supply Voltage V_{CC}	-0.5 to 1.32V	-0.5 to 3.75V
Supply Voltage V_{CCAUX}	-0.5 to 3.75V	-0.5 to 3.75V
Output Supply Voltage V_{CCIO}	-0.5 to 3.75V	-0.5 to 3.75V
I/O Tristate Voltage Applied [4]	-0.5 to 3.75V	-0.5 to 3.75V
Dedicated Input Voltage Applied[4]	-0.5 to 3.75V	-0.5 to 4.25V
Storage Temperature (ambient)	-65 to 150°C	-65 to 150°C
Junction Temp. (Tj)	+125°C	+125°C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice *Thermal Management* document is required.
3. All voltages referenced to GND.
4. Overshoot and undershoot of -2V to (V_{IHMAX} + 2) volts is permitted for a duration of <20ns.

Recommended Operating Conditions[1]

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Core Supply Voltage for 1.2V Devices	1.14	1.26	V
	Core Supply Voltage for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V_{CCAUX}[3]	Auxiliary Supply Voltage	3.135	3.465	V
V_{CCIO}[2]	I/O Driver Supply Voltage	1.14	3.465	V
t_{JCOM}	Junction Temperature Commercial Operation	0	+85	°C
t_{JIND}	Junction Temperature Industrial Operation	-40	100	°C
$t_{JFLASHCOM}$	Junction Temperature, Flash Programming, Commercial	0	+85	°C
$t_{JFLASHIND}$	Junction Temperature, Flash Programming, Industrial	-40	100	°C

1. Like power supplies must be tied together. For example, if V_{CCIO} and V_{CC} are both 2.5V, they must also be the same supply. 3.3V V_{CCIO} and 1.2V V_{CCIO} should be tied to V_{CCAUX} or 1.2V V_{CC} respectively.
2. See recommended voltages by I/O standard in subsequent table.
3. V_{CC} must reach minimum V_{CC} value before V_{CCAUX} reaches 2.5V.

MachXO Programming/Erase Specifications

Symbol	Parameter	Min.	Max.	Units
$N_{PROGCYC}$	Flash Programming Cycles per $t_{RETENTION}$		1,000	Cycles
	Flash Functional Programming Cycles		10,000	Cycles
$t_{RETENTION}$	Data Retention at 125° Junction Temperature	10		Years

MachXO256 and MachXO640 Hot Socketing Specifications[1, 2, 3]

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
I_{DK}	Input or I/O leakage Current	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	—	—	+/-1000	µA

1. Insensitive to sequence of V_{CC}, V_{CCAUX}, and V_{CCIO}. However, assumes monotonic rise/fall rates for V_{CC}, V_{CCAUX}, and V_{CCIO}.
2. $0 \leq V_{CC} \leq V_{CC}$ (MAX), $0 \leq V_{CCIO} \leq V_{CCIO}$ (MAX) and $0 \leq V_{CCAUX} \leq V_{CCAUX}$ (MAX).
3. I_{DK} is additive to I_{PU}, I_{PD} or I_{BH}.

MachXO1200 and MachXO2280 Hot Socketing Specifications[1, 2, 3]

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Non-LVDS General Purpose sysIOs						
I_{DK}	Input or I/O Leakage Current	$0 \leq V_{IN} \leq V_{IH}$ (MAX.)	—	—	+/-1000	µA
LVDS General Purpose sysIOs						
I_{DK_LVDS}	Input or I/O Leakage Current	$V_{IN} \leq V_{CCIO}$	—	—	+/-1000	µA
		$V_{IN} > V_{CCIO}$	—	35	—	mA

1. Insensitive to sequence of V_{CC}, V_{CCAUX}, and V_{CCIO}. However, assumes monotonic rise/fall rates for V_{CC}, V_{CCAUX}, and V_{CCIO}.
2. $0 \leq V_{CC} \leq V_{CC}$ (MAX), $0 \leq V_{CCIO} \leq V_{CCIO}$ (MAX), and $0 \leq V_{CCAUX} \leq V_{CCAUX}$ (MAX).
3. I_{DK} is additive to I_{PU}, I_{PW} or I_{BH}.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{IL}, I_{IH}[1, 4, 5]	Input or I/O Leakage	$0 \leq V_{IN} \leq (V_{CCIO} - 0.2V)$	—	—	10	µA
		$(V_{CCIO} - 0.2V) < V_{IN} \leq 3.6V$	—	—	40	µA
I_{PU}	I/O Active Pull-up Current	$0 \leq V_{IN} \leq 0.7\ V_{CCIO}$	-30	—	-150	µA
I_{PD}	I/O Active Pull-down Current	V_{IL} (MAX) $\leq V_{IN} \leq V_{IH}$ (MAX)	30	—	150	µA
I_{BHLS}	Bus Hold Low sustaining current	$V_{IN} = V_{IL}$ (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High sustaining current	$V_{IN} = 0.7V_{CCIO}$	-30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive current	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	—	—	150	µA
I_{BHHO}	Bus Hold High Overdrive current	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	—	—	-150	µA
V_{BHT}[3]	Bus Hold trip Points	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	V_{IL} (MAX)	—	V_{IH} (MIN)	V
C1	I/O Capacitance[2]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = Typ., V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf
C2	Dedicated Input Capacitance[2]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = Typ., V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. T_A 25°C, f = 1.0MHz
3. Please refer to V_{IL} and V_{IH} in the sysIO Single-Ended DC Electrical Characteristics table of this document.
4. Not applicable to SLEEPN pin.
5. When V_{IH} is higher than V_{CCIO}, a transient current typically of 30ns in duration or less with a peak current of 6mA can occur on the high-to-low transition. For MachXO1200 and MachXO2280 true LVDS output pins, V_{IH} must be less than or equal to V_{CCIO}.

Initialization Supply Current[1, 2, 3, 4]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply	LCMXO256C	13	mA
		LCMXO640C	17	mA
		LCMXO1200C	21	mA
		LCMXO2280C	23	mA
		LCMXO256E	10	mA
		LCMXO640E	14	mA
		LCMXO1200E	18	mA
		LCMXO2280E	20	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LCMXO256E/C	10	mA
		LCMXO640E/C	13	mA
		LCMXO1200E/C	24	mA
		LCMXO2280E/C	25	mA
I_{CCIO}	Bank Power Supply[6]	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all I/O pins are held at V_{CCIO} or GND.
3. Frequency = 0MHz.
4. Typical user pattern.
5. T_J = 25°C, power supplies at nominal voltage.
6. Per Bank, V_{CCIO} = 2.5V. Does not include pull-up/pull-down.

Programming and Erase Flash Supply Current[1, 2, 3, 4]

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply	LCMXO256C	9	mA
		LCMXO640C	11	mA
		LCMXO1200C	16	mA
		LCMXO2280C	22	mA
		LCMXO256E	6	mA
		LCMXO640E	8	mA
		LCMXO1200E	12	mA
		LCMXO2280E	14	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LCMXO256C/E	8	mA
		LCMXO640C/E	10	mA
		LCMXO1200/E	15	mA
		LCMXO2280C/E	16	mA
I_{CCIO}	Bank Power Supply[6]	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all I/O pins are held at V_{CCIO} or GND.
3. Typical user pattern.
4. JTAG programming is at 25MHz.
5. T_J = 25°C, power supplies at nominal voltage.
6. Per Bank. V_{CCIO} = 2.5V. Does not include pull-up/pull-down.

sysIO Differential Electrical Characteristics

LVDS

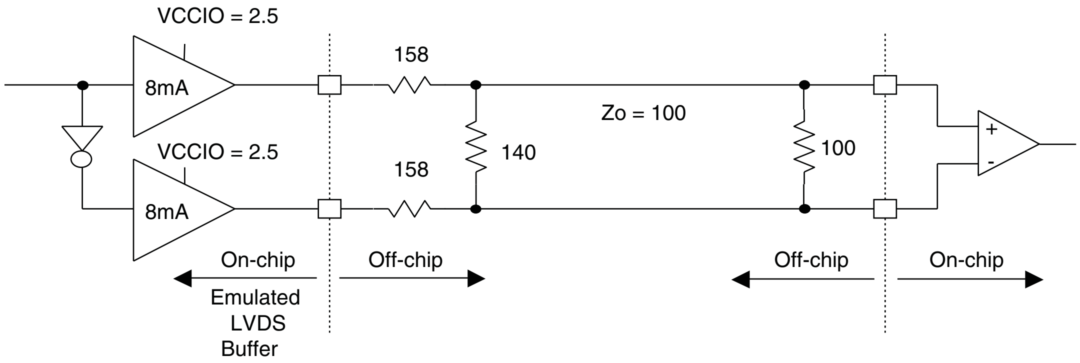
Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input Voltage		0	—	2.4	V
V_{THD}	Differential Input Threshold		+/-100	—	—	mV
V_{CM}	Input Common Mode Voltage	100mV $\le V_{THD}$	$V_{THD}/2$	1.2	1.8	V
		200mV $\le V_{THD}$	$V_{THD}/2$	1.2	1.9	V
		350mV $\le V_{THD}$	$V_{THD}/2$	1.2	2.0	V
I_{IN}	Input current	Power on	—	—	+/-10	µA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	R_T = 100 Ohm	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	R_T = 100 Ohm	0.9V	1.03	—	V
V_{OD}	Output voltage differential	(V_{OP} - V_{OM}), R_T = 100 Ohm	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	(V_{OP} - V_{OM})/2, R_T = 100 Ohm	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	V_{OD} = 0V Driver outputs shorted	—	—	6	mA

LVDS Emulation

MachXO devices can support LVDS outputs via emulation (LVDS25E), in addition to the LVDS support that is available on-chip on certain devices. The output is emulated using complementary LVCMOS outputs in conjunction with resistors across the driver outputs on all devices. The scheme shown in Figure 3-1 is one possible solution for LVDS standard implementation. Resistor values in Figure 3-1 are industry standard values for 1% resistors.

Figure 3-1. LVDS Using External Resistors (LVDS25E)



Note: All resistors are ±1%.

The LVDS differential input buffers are available on certain devices in the MachXO family.

MachXO External Switching Characteristics[1]

Over Recommended Operating Conditions

Parameter	Description	Device	-5		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
General I/O Pin Parameters (Using Global Clock without PLL)[1]									
t_{PD}	Best Case t_{PD} Through 1 LUT	LCMXO256	—	3.5	—	4.2	—	4.9	ns
		LCMXO640	—	3.5	—	4.2	—	4.9	ns
		LCMXO1200	—	3.6	—	4.4	—	5.1	ns
		LCMXO2280	—	3.6	—	4.4	—	5.1	ns
t_{CO}	Best Case Clock to Output - From PFU	LCMXO256	—	4.0	—	4.8	—	5.6	ns
		LCMXO640	—	4.0	—	4.8	—	5.7	ns
		LCMXO1200	—	4.3	—	5.2	—	6.1	ns
		LCMXO2280	—	4.3	—	5.2	—	6.1	ns
t_{SU}	Clock to Data Setup - To PFU	LCMXO256	1.3	—	1.6	—	1.8	—	ns
		LCMXO640	1.1	—	1.3	—	1.5	—	ns
		LCMXO1200	1.1	—	1.3	—	1.6	—	ns
		LCMXO2280	1.1	—	1.3	—	1.5	—	ns
t_H	Clock to Data Hold - To PFU	LCMXO256	-0.3	—	-0.3	—	-0.3	—	ns
		LCMXO640	-0.1	—	-0.1	—	-0.1	—	ns
		LCMXO1200	0.0	—	0.0	—	0.0	—	ns
		LCMXO2280	-0.4	—	-0.4	—	-0.4	—	ns
f_{MAX_IO}	Clock Frequency of I/O and PFU Register	LCMXO256	—	600	—	550	—	500	MHz
		LCMXO640	—	600	—	550	—	500	MHz
		LCMXO1200	—	600	—	550	—	500	MHz
		LCMXO2280	—	600	—	550	—	500	MHz
t_{SKEW_PRI}	Global Clock Skew Across Device	LCMXO256	—	200	—	220	—	240	ps
		LCMXO640	—	200	—	220	—	240	ps
		LCMXO1200	—	220	—	240	—	260	ps
		LCMXO2280	—	220	—	240	—	260	ps

1. General timing numbers based on LVCMOS2.5V, 12 mA.

Rev. A 0.19

sysCLOCK PLL Timing

Over Recommended Operating Conditions

Parameter	Descriptions	Conditions	Min.	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)		25	420	MHz
		Input Divider (M) = 1; Feedback Divider (N) <= $4^{5,6}$	18	25	MHz
f_{OUT}	Output Clock Frequency (CLKOP, CLKOS)		25	420	MHz
f_{OUT2}	K-Divider Output Frequency (CLKOK)		0.195	210	MHz
f_{VCO}	PLL VCO Frequency		420	840	MHz
f_{PFD}	Phase Detector Input Frequency		25	—	MHz
		Input Divider (M) = 1; Feedback Divider (N) <= $4^{5,6}$	18	25	MHz
AC Characteristics					
t_{DT}	Output Clock Duty Cycle	Default duty cycle selected[3]	45	55	%
t_{PH}[4]	Output Phase Accuracy		—	0.05	UI
t_{OPJIT}[1]	Output Clock Period Jitter	f_{OUT} >= 100 MHz	—	+/-120	ps
		f_{OUT} < 100 MHz	—	0.02	UIPP
t_{SK}	Input Clock to Output Clock Skew	Divider ratio = integer	—	+/-200	ps
t_W	Output Clock Pulse Width	At 90% or 10%[3]	1	—	ns
t_{LOCK}[2]	PLL Lock-in Time		—	150	µs
t_{PA}	Programmable Delay Unit		100	450	ps
t_{IPJIT}	Input Clock Period Jitter	$f_{OUT} \geq$ 100 MHz	—	+/-200	ps
		f_{OUT} < 100 MHz	—	0.02	UI
t_{FBKDLY}	External Feedback Delay		—	10	ns
t_{HI}	Input Clock High Time	90% to 90%	0.5	—	ns
t_{LO}	Input Clock Low Time	10% to 10%	0.5	—	ns
t_{RST}	RST Pulse Width		10	—	ns

1. Jitter sample is taken over 10,000 samples of the primary PLL output with a clean reference clock.
2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.
3. Using LVDS output buffers.
4. CLKOS as compared to CLKOP output.
5. When using an input frequency less than 25 MHz the output frequency must be less than or equal to 4 times the input frequency.
6. The on-chip oscillator can be used to provide reference clock input to the PLL provided the output frequency restriction for clock inputs below 25 MHz are followed.

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Switching Test Conditions

Figure 3-6 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Figure 3-5.

Figure 3-6. Output Test Load, LVTTL and LVCMOS Standards

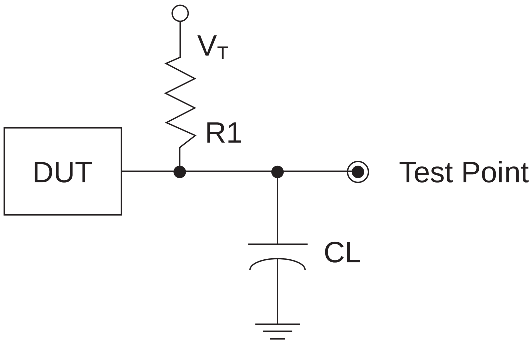

Table 3-5. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R_1	C_L	Timing Ref.	V_T
LVTTL and LVCMOS settings (L -> H, H -> L)	∞	0pF	LVTTL, LVCMOS 3.3 = 1.5V	—
			LVCMOS 2.5 = $V_{CCIO}/2$	—
			LVCMOS 1.8 = $V_{CCIO}/2$	—
			LVCMOS 1.5 = $V_{CCIO}/2$	—
			LVCMOS 1.2 = $V_{CCIO}/2$	—
LVTTL and LVCMOS 3.3 (Z -> H)	188	0pF	1.5	V_{OL}
LVTTL and LVCMOS 3.3 (Z -> L)				V_{OH}
Other LVCMOS (Z -> H)			$V_{CCIO}/2$	V_{OL}
Other LVCMOS (Z -> L)			$V_{CCIO}/2$	V_{OH}
LVTTL + LVCMOS (H -> Z)			V_{OH} - 0.15	V_{OL}
LVTTL + LVCMOS (L -> Z)			V_{OL} - 0.15	V_{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Power Supply and NC

Signal	100 TQFP[1]	144 TQFP[1]	100 csBGA[2]
VCC	**LCMXO256/640**: 35, 90 **LCMXO1200/2280**: 17, 35, 66, 91	21, 52, 93, 129	P7, B6
VCCIO0	**LCMXO256**: 60, 74, 92 **LCMXO640**: 80, 92 **LCMXO1200/2280**: 94	**LCMXO640**: 117, 135 **LCMXO1200/2280**: 135	**LCMXO256**: H14, A14, B5 **LCMXO640**: B12, B5
VCCIO1	**LCMXO256**: 10, 24, 41 **LCMXO640**: 60, 74 **LCMXO1200/2280**: 80	**LCMXO640**: 82, 98 **LCMXO1200/2280**: 117	**LCMXO256**: G1, P1, P10 **LCMXO640**: H14, A14
VCCIO2	**LCMXO256**: None **LCMXO640**: 29, 41 **LCMXO1200/2280**: 70	**LCMXO640**: 38, 63 **LCMXO1200/2280**: 98	**LCMXO256**: None **LCMXO640**: P4, P10
VCCIO3	**LCMXO256**: None **LCMXO640**: 10, 24 **LCMXO1200/2280**: 56	**LCMXO640**: 10, 26 **LCMXO1200/2280**: 82	**LCMXO256**: None **LCMXO640**: G1, P1
VCCIO4	**LCMXO256/640**: None **LCMXO1200/2280**: 44	**LCMXO640**: None **LCMXO1200/2280**: 63	—
VCCIO5	**LCMXO256/640**: None **LCMXO1200/2280**: 27	**LCMXO640**: None **LCMXO1200/2280**: 38	—
VCCIO6	**LCMXO256/640**: None **LCMXO1200/2280**: 20	**LCMXO640**: None **LCMXO1200/2280**: 26	—
VCCIO7	**LCMXO256/640**: None **LCMXO1200/2280**: 6	**LCMXO640**: None **LCMXO1200/2280**: 10	—
VCCAUX	**LCMXO256/640**: 88 **LCMXO1200/2280**: 36, 90	53, 128	B7
GND[3]	**LCMXO256**: 40, 84, 62, 75, 93, 12, 25, 42 **LCMXO640**: 40, 84, 81, 93, 62, 75, 30, 42, 12, 25 **LCMXO1200/2280**: 9, 41, 59, 83, 100, 76, 50, 26	16, 59, 88, 123, 118, 136, 83, 99, 37, 64, 11, 27	**LCMXO256**: N9, B9, G14, B13, A4, H1, N2, N10 **LCMXO640**: N9, B9, A10, A4, G14, B13, N3, N10, H1, N2
NC[4]			—

1. Pin orientation follows the conventional order from pin 1 marking of the top side view and counter-clockwise.
2. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.
3. All grounds must be electrically connected at the board level. For fpBGA and ftBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
4. NC pins should not be connected to any active signals, VCC or GND.

Power Supply and NC (Cont.)

Signal	132 csBGA[1]	256 caBGA / 256 ftBGA[1]	324 ftBGA[1]
VCC	H3, P6, G12, C7	G7, G10, K7, K10	F14, G11, G9, H7, L7, M9
VCCIO0	**LCMXO640**: B11, C5 **LCMXO1200/2280**: C5	**LCMXO640**: F8, F7, F9, F10 **LCMXO1200/2280**: F8, F7	G8, G7
VCCIO1	**LCMXO640**: L12, E12 **LCMXO1200/2280**: B11	**LCMXO640**: H11, G11, K11, J11 **LCMXO1200/2280**: F9, F10	G12, G10
VCCIO2	**LCMXO640**: N2, M10 **LCMXO1200/2280**: E12	**LCMXO640**: L9, L10, L8, L7 **LCMXO1200/2280**: H11, G11	J12, H12
VCCIO3	**LCMXO640**: D2, K3 **LCMXO1200/2280**: L12	**LCMXO640**: K6, J6, H6, G6 **LCMXO1200/2280**: K11, J11	L12, K12
VCCIO4	**LCMXO640**: None **LCMXO1200/2280**: M10	**LCMXO640**: None **LCMXO1200/2280**: L9, L10	M12, M11
VCCIO5	**LCMXO640**: None **LCMXO1200/2280**: N2	**LCMXO640**: None **LCMXO1200/2280**: L8, L7	M8, R9
VCCIO6	**LCMXO640**: None **LCMXO1200/2280**: K3	**LCMXO640**: None **LCMXO1200/2280**: K6, J6	M7, K7
VCCIO7	**LCMXO640**: None **LCMXO1200/2280**: D2	**LCMXO640**: None **LCMXO1200/2280**: H6, G6	H6, J7
VCCAUX	P7, A7	T9, A8	M10, F9
GND[2]	F1, P9, J14, C9, A10, B4, L13, D13, P2, N11, E1, L2	A1, A16, F11, G8, G9, H7, H8, H9, H10, J7, J8, J9, J10, K8, K9, L6, T1, T16	E14, F16, H10, H11, H8, H9, J10, J11, J4, J8, J9, K10, K11, K17, K8, K9, L10, L11, L8, L9, N2, P14, P5, R7
NC[3]	—	**LCMXO640**: E4, E5, F5, F6, C3, C2, G4, G5, H4, H5, K5, K4, M5, M4, P2, P3, N5, N6, M7, M8, N10, N11, R15, R16, P15, P16, M11, L11, N12, N13, M13, M12, K12, J12, F12, F13, E12, E13, D13, D14, B15, A15, C14, B14, E11, E10, E7, E6, D4, D3, B3, B2 **LCMXO1200**: None **LCMXO2280**: None	—

1. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.
2. All grounds must be electrically connected at the board level. For fpBGA and ftBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
3. NC pins should not be connected to any active signals, VCC or GND.

LCMXO256 and LCMXO640 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	LCMXO256				LCMXO640			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
85	PT4B	0	PCLK0_1**	C	PT6B	0	PCLK0_1**	
86	PT4A	0	PCLK0_0**	T	PT5B	0	PCLK0_0**	C
87	PT3D	0		C	PT5A	0		T
88	VCCAUX	-			VCCAUX	-		
89	PT3C	0		T	PT4F	0		
90	VCC	-			VCC	-		
91	PT3B	0		C	PT3F	0		
92	VCCIO0	0			VCCIO0	0		
93	GNDIO0	0			GNDIO0	0		
94	PT3A	0		T	PT3B	0		C
95	PT2F	0		C	PT3A	0		T
96	PT2E	0		T	PT2F	0		C
97	PT2D	0		C	PT2E	0		T
98	PT2C	0		T	PT2B	0		C
99	PT2B	0		C	PT2C	0		
100	PT2A	0		T	PT2A	0		T

* NC for “E” devices.

** Primary clock inputs are single-ended.

LCMXO1200 and LCMXO2280 Logic Signal Connections: 100 TQFP

Pin Number	LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
1	PL2A	7		T	PL2A	7	LUM0_PLLT_FB_A	T
2	PL2B	7		C	PL2B	7	LUM0_PLLC_FB_A	C
3	PL3C	7		T	PL3C	7	LUM0_PLLT_IN_A	T
4	PL3D	7		C	PL3D	7	LUM0_PLLC_IN_A	C
5	PL4B	7			PL4B	7		
6	VCCIO7	7			VCCIO7	7		
7	PL6A	7		T*	PL7A	7		T*
8	PL6B	7	GSRN	C*	PL7B	7	GSRN	C*
9	GND	-			GND	-		
10	PL7C	7		T	PL9C	7		T
11	PL7D	7		C	PL9D	7		C
12	PL8C	7		T	PL10C	7		T
13	PL8D	7		C	PL10D	7		C
14	PL9C	6			PL11C	6		
15	PL10A	6		T*	PL13A	6		T*
16	PL10B	6		C*	PL13B	6		C*
17	VCC	-			VCC	-		
18	PL11B	6			PL14D	6		C
19	PL11C	6	TSALL		PL14C	6	TSALL	T
20	VCCIO6	6			VCCIO6	6		
21	PL13C	6			PL16C	6		
22	PL14A	6	LLM0_PLLT_FB_A	T*	PL17A	6	LLM0_PLLT_FB_A	T*
23	PL14B	6	LLM0_PLLC_FB_A	C*	PL17B	6	LLM0_PLLC_FB_A	C*
24	PL15A	6	LLM0_PLLT_IN_A	T*	PL18A	6	LLM0_PLLT_IN_A	T*
25	PL15B	6	LLM0_PLLC_IN_A	C*	PL18B	6	LLM0_PLLC_IN_A	C*
26**	GNDIO6 GNDIO5	-			GNDIO6 GNDIO5	-		
27	VCCIO5	5			VCCIO5	5		
28	TMS	5	TMS		TMS	5	TMS	
29	TCK	5	TCK		TCK	5	TCK	
30	PB3B	5			PB3B	5		
31	PB4A	5		T	PB4A	5		T
32	PB4B	5		C	PB4B	5		C
33	TDO	5	TDO		TDO	5	TDO	
34	TDI	5	TDI		TDI	5	TDI	
35	VCC	-			VCC	-		
36	VCCAUX	-			VCCAUX	-		
37	PB6E	5		T	PB8E	5		T
38	PB6F	5		C	PB8F	5		C
39	PB7B	4	PCLK4_1****		PB10F	4	PCLK4_1****	
40	PB7F	4	PCLK4_0****		PB10B	4	PCLK4_0****	
41	GND	-			GND	-		

LCMXO1200 and LCMXO2280 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
82	PT9A	1			PT12C	1		T
83	GND	-			GND	-		
84	PT8B	1		C	PT11B	1		C
85	PT8A	1		T	PT11A	1		T
86	PT7D	1	PCLK1_1****		PT10B	1	PCLK1_1****	
87	PT6F	0	PCLK0_0****		PT9B	1	PCLK1_0****	
88	PT6D	0		C	PT8F	0		C
89	PT6C	0		T	PT8E	0		T
90	VCCAUX	-			VCCAUX	-		
91	VCC	-			VCC	-		
92	PT5B	0			PT6D	0		
93	PT4B	0			PT6F	0		
94	VCCIO0	0			VCCIO0	0		
95	PT3D	0		C	PT4B	0		C
96	PT3C	0		T	PT4A	0		T
97	PT3B	0			PT3B	0		
98	PT2B	0		C	PT2B	0		C
99	PT2A	0		T	PT2A	0		T
100**	GNDIO0 GNDIO7	-			GNDIO0 GNDIO7	-		

*Supports true LVDS outputs.
**Double bonded to the pin.
***NC for "E" devices.
****Primary clock inputs are single-ended.

LCMXO256 and LCMXO640 Logic Signal Connections: 100 csBGA (Cont.)

LCMXO256					LCMXO640				
Ball Number	**Ball Function**	**Bank**	**Dual Function**	**Differen-tial**	**Ball Number**	**Ball Function**	**Bank**	**Dual Function**	**Differen-tial**
P13	PB5A	1			P13	PB9C	2		T
M12*	SLEEPN	-	SLEEPN		M12*	SLEEPN	-	SLEEPN	
P14	PB5C	1		T	P14	PB9D	2		C
N13	PB5D	1		C	N13	PB9F	2		
N14	PR9B	0		C	N14	PR11D	1		C
M14	PR9A	0		T	M14	PR11B	1		C
L13	PR8B	0		C	L13	PR11C	1		T
L14	PR8A	0		T	L14	PR11A	1		T
M13	PR7D	0		C	M13	PR10D	1		C
K14	PR7C	0		T	K14	PR10C	1		T
K13	PR7B	0		C	K13	PR10B	1		C
J14	PR7A	0		T	J14	PR10A	1		T
J13	PR6B	0		C	J13	PR9D	1		
H13	PR6A	0		T	H13	PR9B	1		
G14	GNDIO0	0			G14	GNDIO1	1		
G13	PR5D	0		C	G13	PR7B	1		
F14	PR5C	0		T	F14	PR6C	1		
F13	PR5B	0		C	F13	PR6B	1		
E14	PR5A	0		T	E14	PR5D	1		
E13	PR4B	0		C	E13	PR5B	1		
D14	PR4A	0		T	D14	PR4D	1		
D13	PR3D	0		C	D13	PR4B	1		
C14	PR3C	0		T	C14	PR3D	1		
C13	PR3B	0		C	C13	PR3B	1		
B14	PR3A	0		T	B14	PR2D	1		
C12	PR2B	0		C	C12	PR2B	1		
B13	GNDIO0	0			B13	GNDIO1	1		
A13	PR2A	0		T	A13	PT9F	0		C
A12	PT5C	0			A12	PT9E	0		T
B11	PT5B	0		C	B11	PT9C	0		
A11	PT5A	0		T	A11	PT9A	0		
B12	PT4F	0		C	B12	VCCIO0	0		
A10	PT4E	0		T	A10	GNDIO0	0		
B10	PT4D	0		C	B10	PT7E	0		
A9	PT4C	0		T	A9	PT7A	0		
A8	PT4B	0	PCLK0_1**	C	A8	PT6B	0	PCLK0_1**	
B8	PT4A	0	PCLK0_0**	T	B8	PT5B	0	PCLK0_0**	C
A7	PT3D	0		C	A7	PT5A	0		T
B7	VCCAUX	-			B7	VCCAUX	-		
A6	PT3C	0		T	A6	PT4F	0		
B6	VCC	-			B6	VCC	-		
A5	PT3B	0		C	A5	PT3F	0		

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 132 csBGA (Cont.)

LCMXO640					LCMXO1200					LCMXO2280				
Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential
M9	PB7B	2		C	M9	PB9B	4		C	M9	PB12B	4		C
N10	PB7E	2		T	N10	PB9C	4		T	N10	PB12C	4		T
P10	PB7F	2		C	P10	PB9D	4		C	P10	PB12D	4		C
N11	GNDIO2	2			N11	GNDIO4	4			N11	GNDIO4	4		
P11	PB8C	2		T	P11	PB10A	4		T	P11	PB13C	4		T
M11	PB8D	2		C	M11	PB10B	4		C	M11	PB13D	4		C
P12	PB9C	2		T	P12	PB10C	4			P12	PB15B	4		
P13	PB9D	2		C	P13	PB11C	4		T	P13	PB16C	4		T
N12**	SLEEPN	-	SLEEPN		N12**	SLEEPN	-	SLEEPN		N12**	SLEEPN	-	SLEEPN	
P14	PB9F	2			P14	PB11D	4		C	P14	PB16D	4		C
N14	PR11D	1		C	N14	PR16B	3		C	N14	PR19B	3		C
M14	PR11C	1		T	M14	PR15B	3		C*	M14	PR18B	3		C*
N13	PR11B	1		C	N13	PR16A	3		T	N13	PR19A	3		T
M12	PR11A	1		T	M12	PR15A	3		T*	M12	PR18A	3		T*
M13	PR10B	1		C	M13	PR14B	3		C*	M13	PR17B	3		C*
L14	PR10A	1		T	L14	PR14A	3		T*	L14	PR17A	3		T*
L13	GNDIO1	1			L13	GNDIO3	3			L13	GNDIO3	3		
K14	PR8D	1		C	K14	PR12B	3		C*	K14	PR15B	3		C*
K13	PR8C	1		T	K13	PR12A	3		T*	K13	PR15A	3		T*
K12	PR8B	1		C	K12	PR11B	3		C*	K12	PR14B	3		C*
J13	PR8A	1		T	J13	PR11A	3		T*	J13	PR14A	3		T*
J12	PR7C	1			J12	PR10B	3		C*	J12	PR13B	3		C*
H14	PR7B	1		C	H14	PR10A	3		T*	H14	PR13A	3		T*
H13	PR7A	1		T	H13	PR9B	3		C*	H13	PR11B	3		C*
H12	PR6D	1		C	H12	PR9A	3		T*	H12	PR11A	3		T*
G13	PR6C	1		T	G13	PR8B	2		C*	G13	PR10B	2		C*
G14	PR6B	1			G14	PR8A	2		T*	G14	PR10A	2		T*
G12	VCC	-			G12	VCC	-			G12	VCC	-		
F14	PR5D	1		C	F14	PR6C	2			F14	PR8C	2		
F13	PR5C	1		T	F13	PR6B	2		C*	F13	PR8B	2		C*
F12	PR4D	1		C	F12	PR6A	2		T*	F12	PR8A	2		T*
E13	PR4C	1		T	E13	PR5B	2		C*	E13	PR7B	2		C*
E14	PR4B	1			E14	PR5A	2		T*	E14	PR7A	2		T*
D13	GNDIO1	1			D13	GNDIO2	2			D13	GNDIO2	2		
D14	PR3D	1		C	D14	PR4B	2		C*	D14	PR5B	2		C*
D12	PR3C	1		T	D12	PR4A	2		T*	D12	PR5A	2		T*
C14	PR2D	1		C	C14	PR3D	2		C	C14	PR4D	2		C
B14	PR2C	1		T	B14	PR2B	2		C	B14	PR3B	2		C*
C13	PR2B	1		C	C13	PR3C	2		T	C13	PR4C	2		T
A14	PR2A	1		T	A14	PR2A	2		T	A14	PR3A	2		T*
A13	PT9F	0		C	A13	PT11D	1		C	A13	PT16D	1		C
A12	PT9E	0		T	A12	PT11B	1		C	A12	PT16B	1		C
B13	PT9D	0		C	B13	PT11C	1		T	B13	PT16C	1		T
B12	PT9C	0		T	B12	PT10F	1			B12	PT15D	1		
C12	PT9B	0		C	C12	PT11A	1		T	C12	PT16A	1		T
A11	PT9A	0		T	A11	PT10D	1		C	A11	PT14B	1		C
C11	PT8C	0			C11	PT10C	1		T	C11	PT14A	1		T
A10	GNDIO0	0			A10	GNDIO1	1			A10	GNDIO1	1		
B10	PT7F	0		C	B10	PT9F	1		C	B10	PT12F	1		C
C10	PT7E	0		T	C10	PT9E	1		T	C10	PT12E	1		T

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 256 caBGA / 256 ftBGA (Cont.)

LCMXO640					LCMXO1200					LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
E11	NC				E11	PT10D	1		C	E11	PT15B	1		C
E10	NC				E10	PT10C	1		T	E10	PT15A	1		T
D12	PT9D	0		C	D12	PT10B	1		C	D12	PT14D	1		C
D11	PT9C	0		T	D11	PT10A	1		T	D11	PT14C	1		T
A14	PT7F	0		C	A14	PT9F	1		C	A14	PT14B	1		C
A13	PT7E	0		T	A13	PT9E	1		T	A13	PT14A	1		T
C12	PT8B	0		C	C12	PT9D	1		C	C12	PT13D	1		C
C11	PT8A	0		T	C11	PT9C	1		T	C11	PT13C	1		T
-	-				VCCIO1	VCCIO1	1			VCCIO1	VCCIO1	1		
-	-				GND	GNDIO1	1			GND	GNDIO1	1		
B12	PT7B	0		C	B12	PT9B	1		C	B12	PT12D	1		C
B11	PT7A	0		T	B11	PT9A	1		T	B11	PT12C	1		T
A12	PT7D	0		C	A12	PT8F	1		C	A12	PT12B	1		C
A11	PT7C	0		T	A11	PT8E	1		T	A11	PT12A	1		T
GND	GND	-			GND	GND	-			GND	GND	-		
B10	PT5D	0		C	B10	PT8D	1		C	B10	PT11B	1		C
B9	PT5C	0		T	B9	PT8C	1		T	B9	PT11A	1		T
D10	PT8D	0		C	D10	PT8B	1		C	D10	PT10F	1		C
D9	PT8C	0		T	D9	PT8A	1		T	D9	PT10E	1		T
-	-				VCCIO1	VCCIO1	1			VCCIO1	VCCIO1	1		
-	-				GND	GNDIO1	1			GND	GNDIO1	1		
C10	PT6D	0		C	C10	PT7F	1		C	C10	PT10D	1		C
C9	PT6C	0		T	C9	PT7E	1		T	C9	PT10C	1		T
A9	PT6B	0	PCLK0_1***	C	A9	PT7D	1	PCLK1_1***	C	A9	PT10B	1	PCLK1_1***	C
A10	PT6A	0		T	A10	PT7C	1		T	A10	PT10A	1		T
E9	PT9B	0		C	E9	PT7B	1		C	E9	PT9D	1		C
E8	PT9A	0		T	E8	PT7A	1		T	E8	PT9C	1		T
D7	PT5B	0	PCLK0_0***	C	D7	PT6F	0	PCLK1_0***	C	D7	PT9B	1	PCLK1_0***	C
D8	PT5A	0		T	D8	PT6E	0		T	D8	PT9A	1		T
VCCIO0	VCCIO0	0			VCCIO0	VCCIO0	0			VCCIO0	VCCIO0	0		
GND	GNDIO0	0			GND	GNDIO0	0			GND	GNDIO0	0		
C8	PT4F	0		C	C8	PT6D	0		C	C8	PT8D	0		C
B8	PT4E	0		T	B8	PT6C	0		T	B8	PT8C	0		T
A8	VCCAUX	-			A8	VCCAUX	-			A8	VCCAUX	-		
A7	PT4D	0		C	A7	PT6B	0		C	A7	PT7D	0		C
A6	PT4C	0		T	A6	PT6A	0		T	A6	PT7C	0		T
VCC	VCC	-			VCC	VCC	-			VCC	VCC	-		
B7	PT4B	0		C	B7	PT5F	0		C	B7	PT7B	0		C
B6	PT4A	0		T	B6	PT5E	0		T	B6	PT7A	0		T
C6	PT3C	0		T	C6	PT5C	0		T	C6	PT6A	0		T
C7	PT3D	0		C	C7	PT5D	0		C	C7	PT6B	0		C
A5	PT3E	0		T	A5	PT5A	0		T	A5	PT6C	0		T
A4	PT3F	0		C	A4	PT5B	0		C	A4	PT6D	0		C
E7	NC				E7	PT4C	0		T	E7	PT6E	0		T
E6	NC				E6	PT4D	0		C	E6	PT6F	0		C
B5	PT3B	0		C	B5	PT3F	0		C	B5	PT5D	0		C
B4	PT3A	0		T	B4	PT3E	0		T	B4	PT5C	0		T
D5	PT2D	0		C	D5	PT3D	0		C	D5	PT5B	0		C
D6	PT2C	0		T	D6	PT3C	0		T	D6	PT5A	0		T
C4	PT2E	0		T	C4	PT4A	0		T	C4	PT4A	0		T
C5	PT2F	0		C	C5	PT4B	0		C	C5	PT4B	0		C
-	-	-			-	-	-			GND	GND	-		
D4	NC				D4	PT2D	0		C	D4	PT3D	0		C

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following:

- Thermal Management document
- TN1090 - Power Estimation and Management for MachXO Devices
- Power Calculator tool included with the Lattice ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256E-3T100I	256	1.2V	78	-3	TQFP	100	IND
LCMXO256E-4T100I	256	1.2V	78	-4	TQFP	100	IND
LCMXO256E-3M100I	256	1.2V	78	-3	csBGA	100	IND
LCMXO256E-4M100I	256	1.2V	78	-4	csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640E-3T100I	640	1.2V	74	-3	TQFP	100	IND
LCMXO640E-4T100I	640	1.2V	74	-4	TQFP	100	IND
LCMXO640E-3M100I	640	1.2V	74	-3	csBGA	100	IND
LCMXO640E-4M100I	640	1.2V	74	-4	csBGA	100	IND
LCMXO640E-3T144I	640	1.2V	113	-3	TQFP	144	IND
LCMXO640E-4T144I	640	1.2V	113	-4	TQFP	144	IND
LCMXO640E-3M132I	640	1.2V	101	-3	csBGA	132	IND
LCMXO640E-4M132I	640	1.2V	101	-4	csBGA	132	IND
LCMXO640E-3B256I	640	1.2V	159	-3	caBGA	256	IND
LCMXO640E-4B256I	640	1.2V	159	-4	caBGA	256	IND
LCMXO640E-3FT256I	640	1.2V	159	-3	ftBGA	256	IND
LCMXO640E-4FT256I	640	1.2V	159	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200E-3T100I	1200	1.2V	73	-3	TQFP	100	IND
LCMXO1200E-4T100I	1200	1.2V	73	-4	TQFP	100	IND
LCMXO1200E-3T144I	1200	1.2V	113	-3	TQFP	144	IND
LCMXO1200E-4T144I	1200	1.2V	113	-4	TQFP	144	IND
LCMXO1200E-3M132I	1200	1.2V	101	-3	csBGA	132	IND
LCMXO1200E-4M132I	1200	1.2V	101	-4	csBGA	132	IND
LCMXO1200E-3B256I	1200	1.2V	211	-3	caBGA	256	IND
LCMXO1200E-4B256I	1200	1.2V	211	-4	caBGA	256	IND
LCMXO1200E-3FT256I	1200	1.2V	211	-3	ftBGA	256	IND
LCMXO1200E-4FT256I	1200	1.2V	211	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280E-3T100I	2280	1.2V	73	-3	TQFP	100	IND
LCMXO2280E-4T100I	2280	1.2V	73	-4	TQFP	100	IND
LCMXO2280E-3T144I	2280	1.2V	113	-3	TQFP	144	IND
LCMXO2280E-4T144I	2280	1.2V	113	-4	TQFP	144	IND
LCMXO2280E-3M132I	2280	1.2V	101	-3	csBGA	132	IND
LCMXO2280E-4M132I	2280	1.2V	101	-4	csBGA	132	IND
LCMXO2280E-3B256I	2280	1.2V	211	-3	caBGA	256	IND
LCMXO2280E-4B256I	2280	1.2V	211	-4	caBGA	256	IND
LCMXO2280E-3FT256I	2280	1.2V	211	-3	ftBGA	256	IND
LCMXO2280E-4FT256I	2280	1.2V	211	-4	ftBGA	256	IND
LCMXO2280E-3FT324I	2280	1.2V	271	-3	ftBGA	324	IND
LCMXO2280E-4FT324I	2280	1.2V	271	-4	ftBGA	324	IND

MachXO Family Data Sheet
Revision History

June 2013 **Data Sheet DS1002**

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
October 2005	01.1	Introduction	Distributed RAM information in family table updated. Added footnote 1 - fpBGA packaging to the family selection guide.
		Architecture	sysIO Buffer section updated.
			Hot Socketing section updated.
			Sleep Mode section updated.
			SLEEP Pin Characteristics section updated.
			Oscillator section updated.
			Security section updated.
		DC and Switching Characteristics	Recommended Operating Conditions table updated.
			DC Electrical Characteristics table updated.
			Supply Current (Sleep Mode) table added with LCMXO256/640 data.
			Supply Current (Standby) table updated with LCMXO256/640 data.
			Initialization Supply Current table updated with LCMXO256/640 data.
			Programming and Erase Flash Supply Current table updated with LCMXO256/640 data.
			Register-to-Register Performance table updated (rev. A 0.16).
			External Switching Characteristics table updated (rev. A 0.16).
			Internal Timing Parameter table updated (rev. A 0.16).
			Family Timing Adders updated (rev. A 0.16).
			sysCLOCK Timingupdated (rev. A 0.16).
			MachXO "C" Sleep Mode Timing updated (A 0.16).
			JTAG Port Timing Specification updated (rev. A 0.16).
		Pinout Information	SLEEPIN description updated.
			Pin Information Summary updated.
			Power Supply and NC Connection table has been updated.
			Logic Signal Connection section has been updated to include all devices/packages.
		Ordering Information	Part Number Description section has been updated.
			Ordering Part Number section has been updated (added LCMXO256C/ LCMXO640C "4W").
		Supplemental Information	MachXO Density Migration Technical Note (TN1097) added.
November 2005	01.2	Pinout Information	Added “Power Supply and NC Connections” summary information for LCMXO1200 and LCMXO2280 in 100 TQFP package.
December 2005	01.3	DC and Switching Characteristics	Supply Current (Standby) table updated with LCMXO1200/2280 data.
		Ordering Information	Ordering Part Number section updated (added LCMXO2280C "4W").
April 2006	02.0	Introduction	Introduction paragraphs updated.
		Architecture	Architecture Overview paragraphs updated.